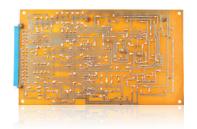


Printed Circuit Board Solutions

As a buyer or design engineer, your challenge is to find high quality, competitively priced printed circuit boards and interconnect solutions for your end product. With over 25 years of experience in PCB technology, design optimization, and manufacturability, Vexos' dedicated team of PCB professionals will provide you with the most innovative and cost-effective solutions for your frontend design through mass production.









Competitive Prices

Our experienced team of PCB professionals works closely with state-of-the-art manufacturing partners to offer the most competitive prices in the market while ensuring that all boards are built to global quality standards. With extensive knowledge of industry requirements and specifications, the Vexos PCB team will also assist with design and engineering specifications to improve feasibility and manufacturability and help identify cost reduction opportunities.

Advanced Technology

From standard technology to complex, highdensity circuits incorporating the latest technology, Vexos will keep you up-to-date with cutting edge advancements available in the market today.

- · Conventional rigid circuits
- Rigid circuits with buried via holes and blind via holes
- HDI rigid circuit with 1+n+1 / 2+n+2 / 3+n+3 / ELIC structure
- Semi-flex PCBs
- RF PCBs
- Flex circuits
- Rigid-flex circuits
- Metal, aluminum, copper, ceramic and steelbased PCBs
- Heavy copper and bondable PCBs

Capabilities

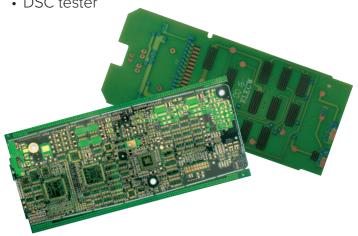
- Rapid prototyping
- Rigid boards from 1 to 48 layers
- Flex circuits from 1 to 8 layers
- HDI from 4 to 20 layers
- Rigid-Flex from 4 to 16 layers with laser drills
- Controlled Impedance: +/-8%
- Thin laminate capability down to 2 mil
- HAL, lead-free HAL, Flash gold, ENIG, ENEPIG, gold finger plating, selective gold plating, Entek, immersion tin, immersion silver surface finishes
- Silver ink through holes, silver and carbon ink jumper, carbon printing, peelable solder mask
- Materials: CEM-1, CEM-3, FR-1, FR-2, FR-4, FR-5 (High Tg), High Tg Material (Tg = 180° C), BT, Rogers, Panasonic, ISOLA, polyamide, and ceramic material
- Finished board thickness: 0.25 mm / 0.010 inch to 7.0 mm / 0.275 inch
- Copper thickness up to 10 oz
- Hole size: 0.1 mm/0.004 inch minimum for laser vias, and 0.15 mm/0.006 minimum for mechanic drilling
- Trace size: 0.076 mm/0.003 inch minimum for conventional PCBs, 0.05mm/0.002 minimum for HDI/ELIC
- Trace spacing: 0.076 mm/0.003 inch minimum for conventional PCBs, 0.05mm/0.002 minimum for HDI/ELIC
- Aspect ratio: 15:1

Equipment

Our quality equipment includes:

- Optical projectors
- · X-Ray metal thickness measuring equipment
- Flying Probe Tester
- Universal electrical tester
- Omega meter
- AOI equipment
- Micro-section equipment
- Humidity chamber
- Impedance tester
- Contamination tester
- · Bonding machine
- TDR equipment
- Hi-pot test equipment
- AA spectrum measurement
- Capacitance meter
- X-ray fluorescence inspection equipment
- · Reflow oven
- Auto E-tester
- CMI 700 copper thickness tester
- · Peel strength tester
- Gel-time tester
- IST tester
- · RoHS XRF tester





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Dependable Quality

Vexos achieves the highest quality levels by utilizing the latest equipment, processes, quality standards and certifications across the organization; to enable a flawless launch of each individual program.

- · Rigorous selection of sub-contractors or partner factories
- Performance evaluation and monitoring through regular audits of the factories
- Continuous training for personnel at all levels
- Document control to safeguard your data and release of technical documents
- Sample approval process including production part approval process (PPAP)

Certifications & Awards

- ISO 9001:2015
- ISO 13485:2016
- ISO 14001:2015
- FDA registered
- OHSAS 18001:2007
- RoHS and Non-RoHS
- IATF 16949:2016
- CGP certification

Markets We Serve



COMMUNICATIONS



INDUSTRIAL



MEDICAL



SMART GRID



SECURITY



AUTOMOTIVE



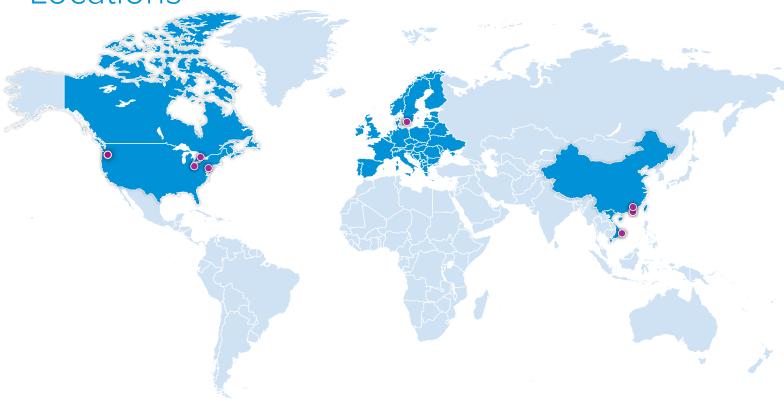
COMPUTING



AVIATION DEFENSE SPACE



Locations



USA

LAGRANGE, OHIO, USA

MANUFACTURING FACILITY 110 Commerce Drive LaGrange, OH 44050, USA +1 440-284-2500

VANCOUVER, WASHINGTON, USA

MANUFACTURING FACILITY

VEXOS I CONTROLTEK 3905 NE 112 Avenue, Vancouver, WA 98682 +1 360.896.9375

CANADA

MARKHAM, ONTARIO, CANADA

MANUFACTURING FACILITY 195 Royal Crest Court Markham, Ontario, Canada L3R 9X6 +1 905-479-6203

EUROPE

MALMÖ, SWEDEN

EUROPEAN SALES OFFICE WTC Building, Skeppsgatan 19 SE-211 11 Malmö, Sweden +46 705 48 26 59

ASIA

DONGGUAN, CHINA

MANUFACTURING FACILITY Block A, Plainvim Industrial Park, Dongkeng Avenue, Dongkeng Town Dongguan City, Guangdong, PRC, 523455 +86 769 8101 5368

HO CHI MINH CITY, VIETNAM

MANUFACTURING FACILITY Floor 4th, Standard factory B, Tan Thuan street, Tan Thuan EPZ, Tan Thuan Dong ward, District 7, Ho Chi Minh City,

72909, Vietnam +84 28 3636 2939

HONG KONG

ASIA LOGISTICS Flat A, 11/F Wing Tai Centre 12 Hing Yip Street Kwun Tong Kowloon, Hong Kong +852 2304 7900

WINNER OF CIRCUITS ASSEMBLY AWARDS







